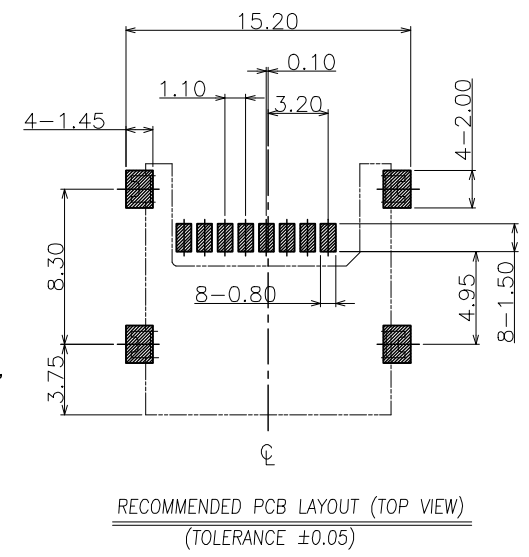
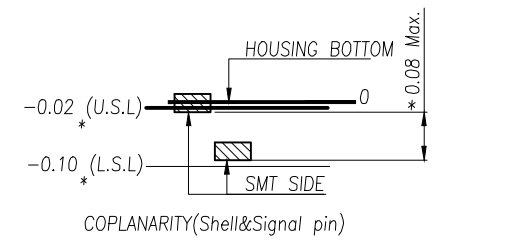


- NOTES:
- FINISH:
 - 1-1.CONTACT: Au 1u" PLATING ON CONTACT AREA, 100~200u" Sn PLATING ON SOLDER TAILS, 50u" NICKEL UNDERPLATING VOER ALL;
 - 1-2.SHELL: NO PLATING;
 - PRODUCT SPECIFICATIONS:
 - 2-1.VOLTAGE RATING: 100V
 - 2-2.CURRENT RATING: 0.5A
 - 2-3.INSULATION RESISTANCE: 1000 MEG.OHM MIN
 - 2-4.CONTACT RESISTANCE: 100 MILL.OHM MAX
 - 2-5.OPERATION TEMPERATURE: -20° TO +85°



东莞市訊普電子科技有限公司			
E	PRODUCT SPEC. T 卡		
TITLE:	micro sd H1.8 鐵殼 T 卡		
PART NO.	TF-102-18		
FILE NAME.			
SCALE	1:1	UNIT:mm	A4 SHEET: 1 of 1

工程变更通知单号 ECN(DCN) NO.	版次 REV	日期 DATE	说明 DESCRIPTION	改变 CHANGE	承认 APPRO.	General X±0.50 .X±0.30 .XX±0.20	Angle X°±2° .X°±1° .XX°±0.5°	设计 DESIGN	校阅 CHECK	承认 APPRO.
	C	16'/05/25	修改铁壳长度	赵文博				fzp		13'/11/30
	B	13'/12/30	修改铁壳材料厚度为0.20	fzp				wangyong		13'/11/30
	A	13'/11/30	新发行					wangyong		13'/11/30
GENERAL TOLERANCE UNLESS OTHERWISE NOTED										